

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology
- ★ 100% EAS Guaranteed

Product Summary

RoHS

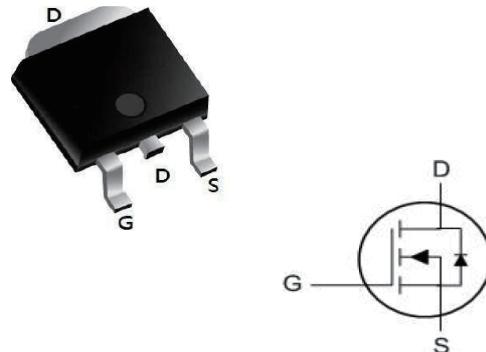
BVDSS	RDSON	ID
30V	15mΩ	20A

Description

The 20N03 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The 20N03 meet the RoHS and Green Product, requirement 100% EAS guaranteed with full function reliability approved.

TO252 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		10s	Steady State	
V_{DS}	Drain-Source Voltage	30		V
V_{GS}	Gate-Source Voltage	± 20		V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	20		A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	8		A
I_{DM}	Pulsed Drain Current ²	38		A
E_{AS}	Single Pulse Avalanche Energy ³	28		mJ
I_{AS}	Avalanche Current	13.8		A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation ⁴	5.5		W
T_{STG}	Storage Temperature Range	-55 to 175		°C
T_J	Operating Junction Temperature Range	-55 to 175		°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R_{eJC}	Thermal Resistance Junction-Case ¹	---	36	°C/W

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristics						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}, I_D=250\ \mu\text{A}$	30	-	-	V
$I_{DS(on)}$	Zero Gate Voltage Drain Current	$V_{DS}=30\text{V}, V_{GS}=0\text{V},$	-	-	1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS}=0\text{V}, V_{GS}=\pm 20\text{V}$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\ \mu\text{A}$	1	1.5	2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance note ³	$V_{GS}=10\text{V}, I_D=5\text{A}$	-	15	20	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=3\text{A}$	-	21	29	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=10\text{V}, V_{GS}=0\text{V}, f=1.0\text{MHz}$	-	490	-	pF
C_{oss}	Output Capacitance		-	79	-	
C_{rss}	Reverse Transfer Capacitance		-	61	-	
Q_g	Total Gate Charge	$V_{DS}=15\text{V}, I_D=5.8\text{A}, V_{GS}=10\text{V}$	-	10	-	nC
Q_{gs}	Gate-Source Charge		-	1.7	-	
Q_{gd}	Gate-Drain("Miller") Charge		-	2.5	-	
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS}=15\text{V}, I_D=3\text{A}, R_{GEN}=3\ \Omega, V_{GS}=10\text{V}$	-	6	-	ns
t_r	Turn-on Rise Time		-	15	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	17	-	ns
t_f	Turn-off Fall Time		-	17	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current	-	-	9	-	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	36	-	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}, I_S=9\text{A}$	-	-	1.2	V
t_{rr}	Body Diode Reverse Recovery Time	$IF=5\text{A}, dI/dt=100\text{A}/\mu\text{s}$	-	7	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	2	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. EAS condition: $T_J=25^\circ\text{C}, V_{DD}=10\text{V}, V_G=4.5\text{V}, R_G=25\Omega, L=0.5\text{mH}, I_{AS}=6\text{A}$
3. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

Typical Performance Characteristics

Figure 1: Output Characteristics

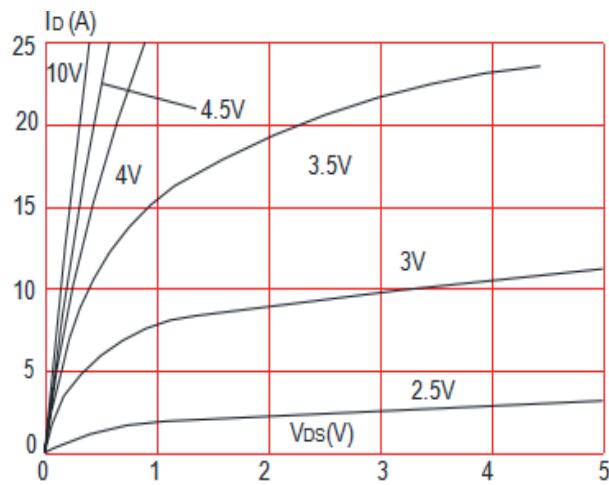


Figure 2: Typical Transfer Characteristics

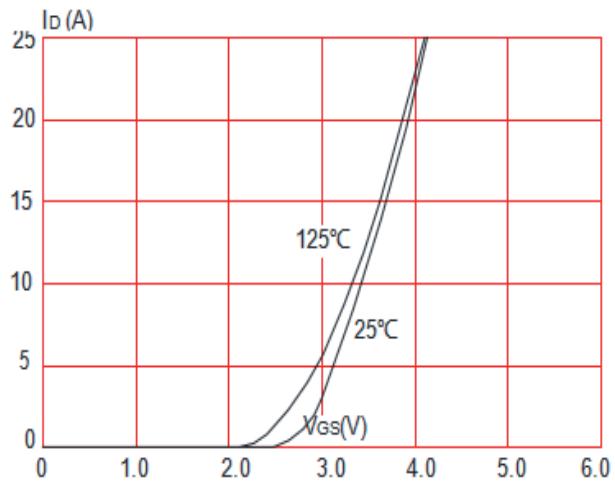


Figure 3: On-resistance vs. Drain Current

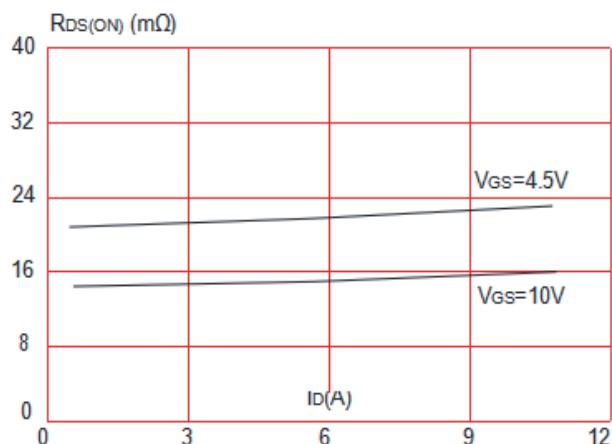


Figure 5: Gate Charge Characteristics

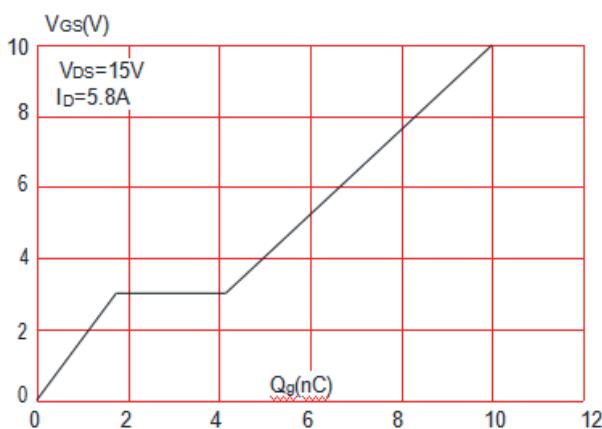


Figure 4: Body Diode Characteristics

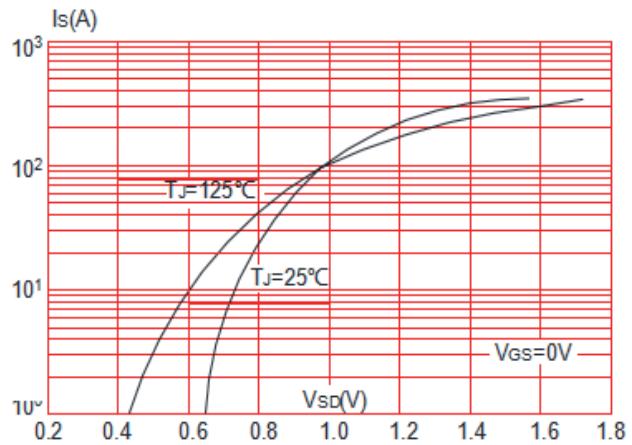
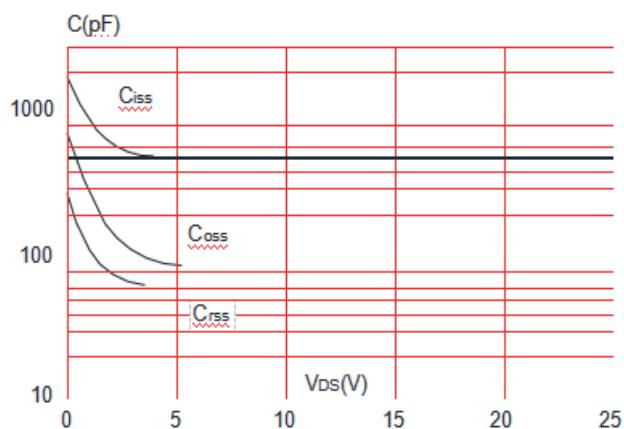


Figure 6: Capacitance Characteristics



Typical Performance Characteristics

Figure 7: Normalized Breakdown Voltage

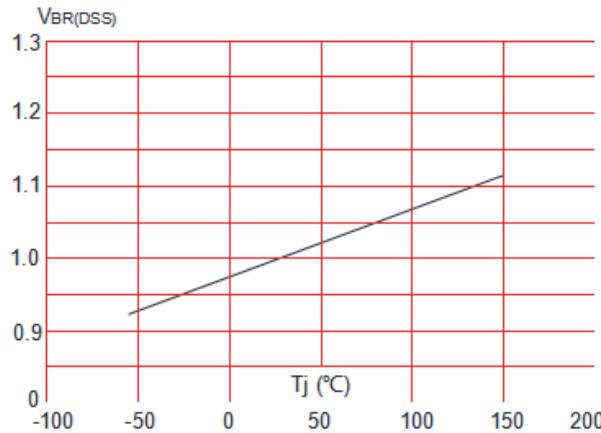
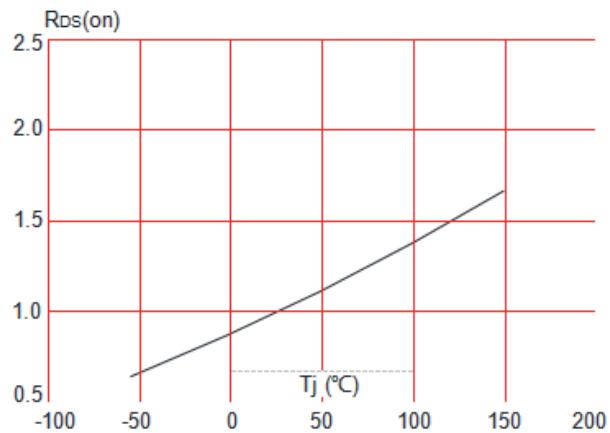

Figure 8: Normalized on Resistance vs. J_D


Figure 9: Maximum Safe Operating Area

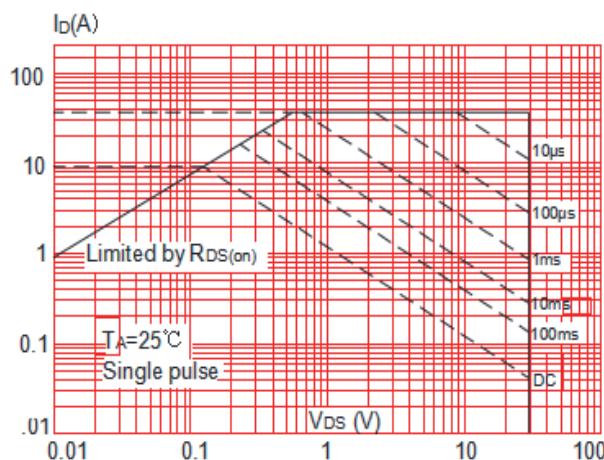


Figure 10: Maximum Continuous Drain Current

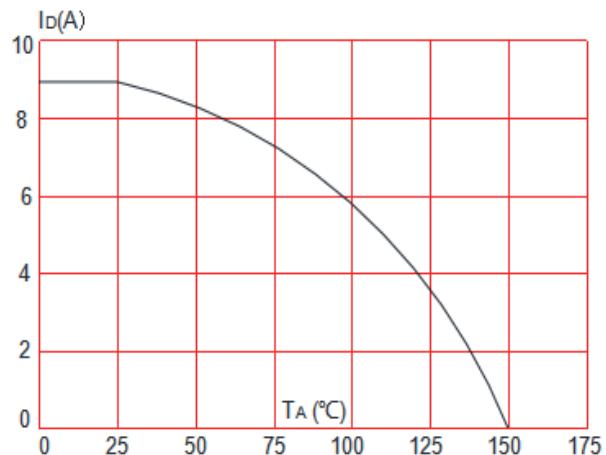
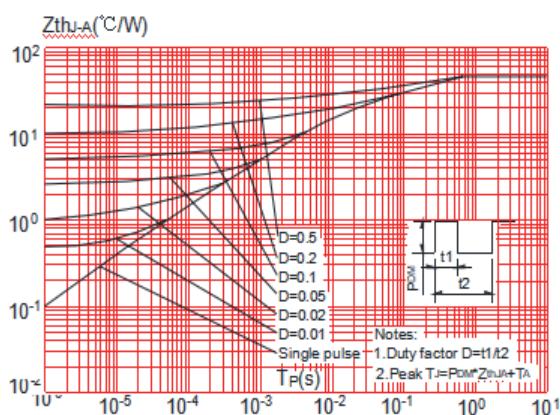


Figure 11: Maximum Effective Transient Thermal Resistance



Test Circuit

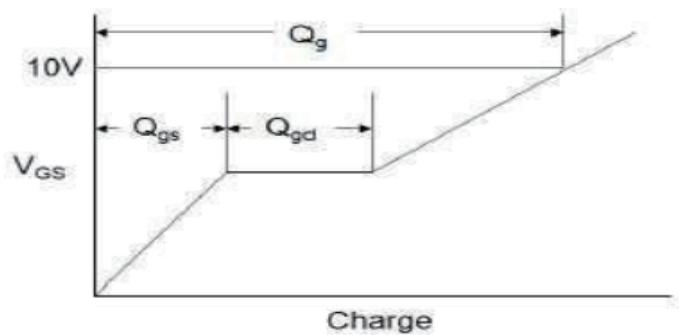
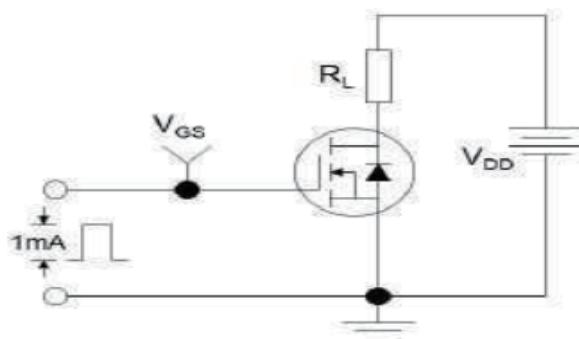


Figure 1: Gate Charge Test Circuit & Waveform

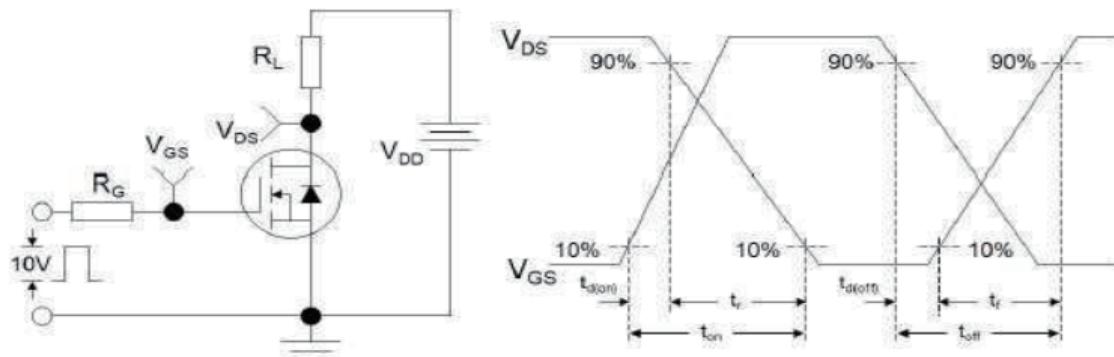


Figure 2: Resistive Switching Test Circuit & Waveforms

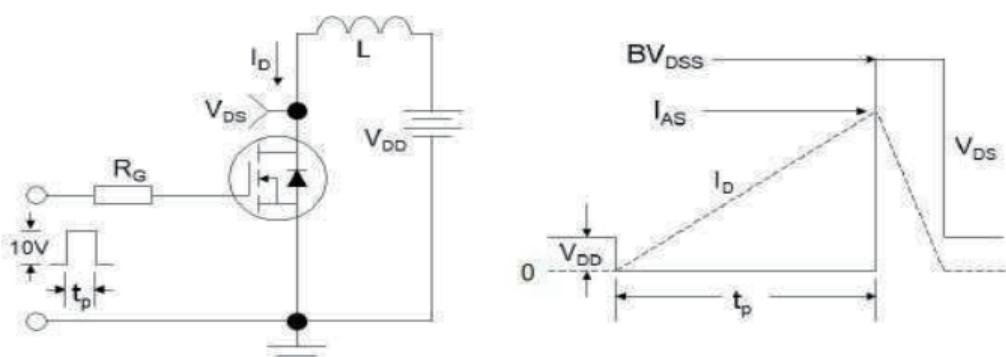
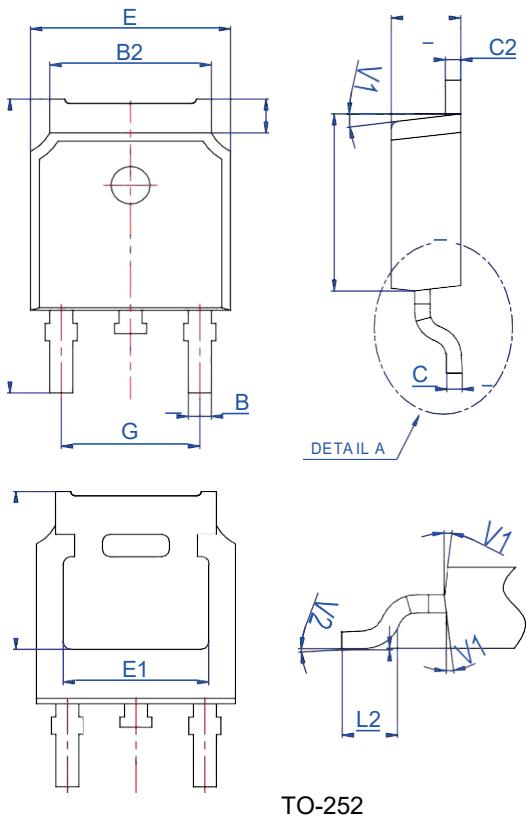


Figure 3: Unclamped Inductive Switching Test Circuit & Waveforms

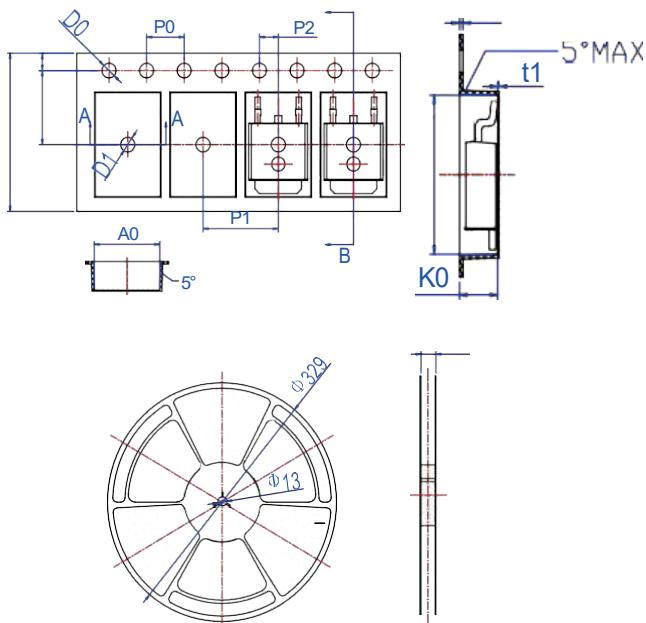


Package Mechanical Data-TO-252-4R



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.1		2.5	0.083		0.098
A2	0		0.1	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.4		0.6	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.9		6.3	0.232		0.248
D1	5.30REF			0.209REF		
E	6.4		6.8	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.5		10.7	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Reel Specification-TO-252-4R



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.9	16	16.1	0.626	0.63	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.4	7.5	7.6	0.291	0.295	0.299
D0	1.4	1.5	1.6	0.055	0.059	0.063
D1	1.4	1.5	1.6	0.055	0.059	0.063
P0	3.9	4	4.1	0.154	0.157	0.161
P1	7.9	8	8.1	0.311	0.315	0.319
P2	1.9	2	2.1	0.075	0.079	0.083
A0	6.85	6.9	7	0.27	0.271	0.276
B0	10.45	10.5	10.6	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.1			0.004		
10P0	39.8	40	40.2	1.567	1.575	1.583